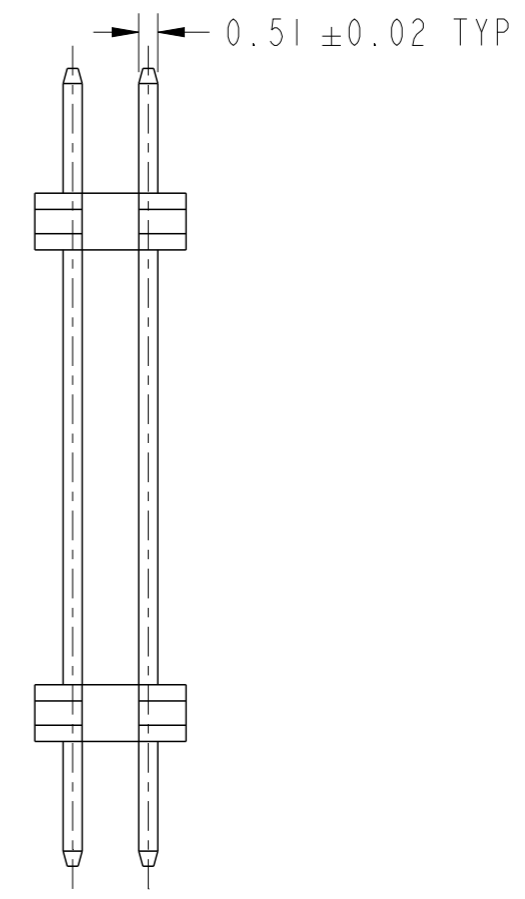
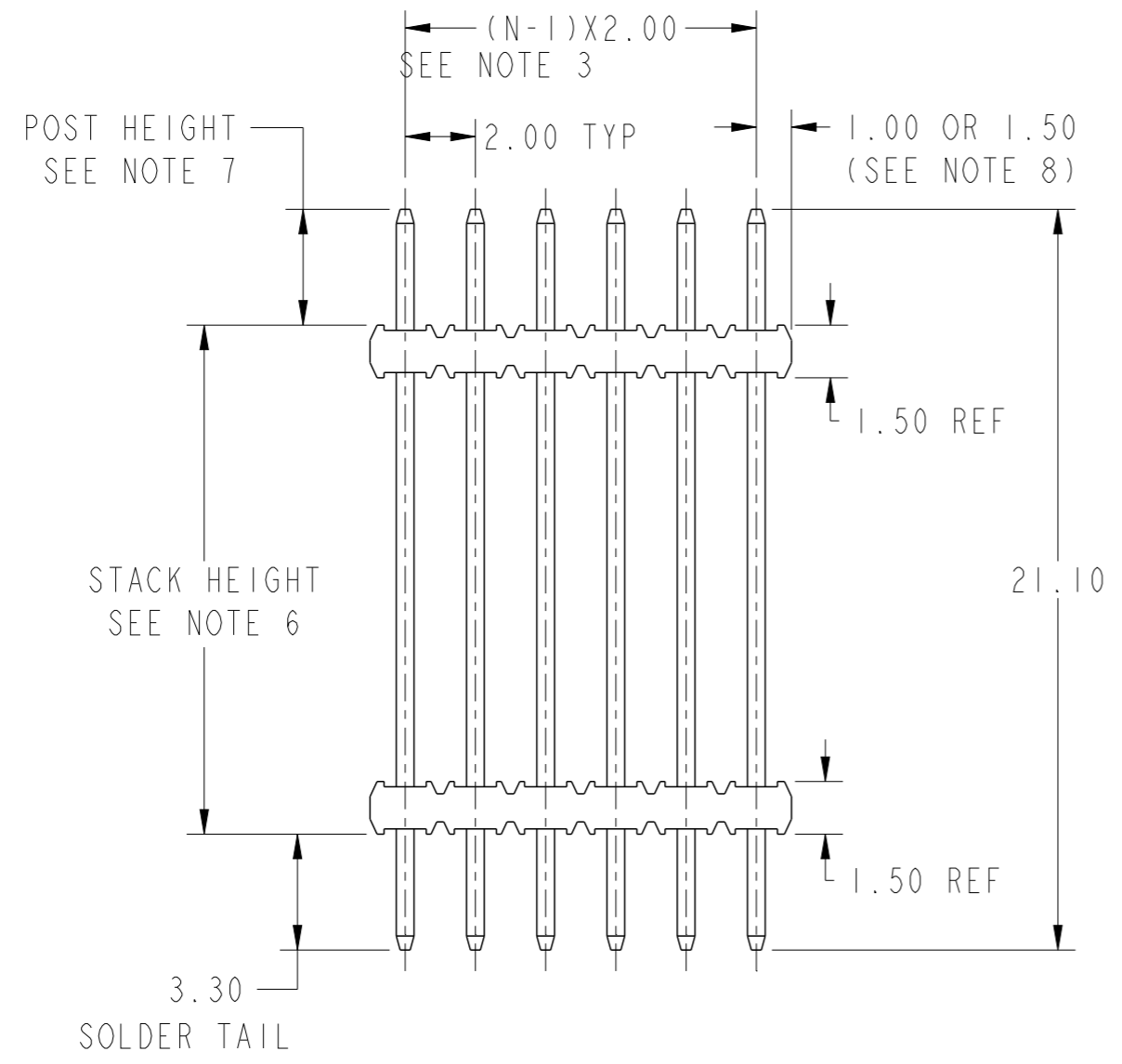


RECOMMENDED HOLE PATTERN)



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| | | | | | | | | | | |
|---------------------------------------|--|---------|-------------|------------|-------------|----------------|-----------------|----|------------------------|-----|
| spec ref | | dr | Guo-Min Sun | 2013/05/15 | projection | MM | size | A3 | scale | 5:1 |
| tolerance std | | eng | Guo-Min Sun | 2013/07/18 | | | ecn no | | ELX-N-14964-1 | |
| TOLERANCES UNLESS OTHERWISE SPECIFIED | | chr | - | - | | | rel level | | Released | |
| surface | | linear | 0.X | ±0.50 | | product family | dwg no | | 10121036 | |
| | | | 0.XX | ±0.25 | | | rev | | B | |
| | | | 0.XXX | ±0.15 | | | cat. no. | | Product - Customer Drw | |
| | | angular | 0° | ±3° | www.fci.com | | STATUS:Released | | Printed: Jul 22, 2013 | |

PRODUCT NUMBER DESCRIPTION:
10121036 - X XX X XXX LF

PLATING

S = 0.38um GOLD
ON CONTACT AREA
0.38um GOLD ON TAIL
G = 0.76um GOLD
ON CONTACT AREA
0.76um GOLD ON TAIL
F = 0.20um GOLD
ON CONTACT AREA
0.20um GOLD ON TAIL
T = 0.76um GOLD
ON CONTACT AREA
2.54um 100% MATTE TIN ON TAIL

LEAD FREE

STACK HEIGHT (SEE NOTE 6)

PACKAGING: - = BAGS
(SEE NOTE 5) U = TUBES

POSITIONS PER ROW (02 TO 25)

NOTES:

- MATERIAL HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL 94V-0, COLOR BLACK
- MATERIAL TERMINAL: COPPER ALLOY
- TO DETERMINE DIMENSIONS:
N=NUMBER OF POSITIONS PER ROW
EX.: 10 POS., N x 2.00 = 20.00 TOTAL POSITIONS
- 0.2kg MIN. PIN RETENTION IN EITHER DIRECTION.
- PACKAGING;
(A) STANDARD PACKAGING: IN POLY BAGS.
(B) SPECIAL PACKAGING: IN TUBE.
FOR ALL SPECIAL PACKAGING,FCI MUST BE CONTACTED FOR
AVAILABILITY IN SIZE REQUESTED.
- STACK HEIGHT IS DETERMINED BY CUSTOMER APPLICATION REQUIREMENTS.
SPECIFIED IN mm. EXAMPLE: 3.7mm STACK
HEIGHT=10121036-XXXX037XLF.

- POST LENGTH IS DETERMINED BY: (OAL)-(3.30)-(STACK HGT.)=POST
LENGTH. MINIMUM MATING LENGTH TO BE 2.0mm
- DIM 1.0 APPLIES TO MOLDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN,
DIM 1.5 MAX APPLIES.
- OMIT FROM PRODUCT NUMBER IF FEATURE IS NOT APPLICABLE.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 255~C PEAK
TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED
OR VAPOR PHASE REFLOW OVEN.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260~C PEAK
TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER
APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

| | | | | | | | | |
|------|-------------|--------------------------|----------------|--------|-------------|---------------|-------|------------------------|
| dr | Guo-Min Sun | 2013/05/15 | projection | MM | size | A3 | scale | 1:1 |
| eng | Guo-Min Sun | 2013/07/18 | | | ecn no | ELX-N-14964-1 | | |
| chr | - | - | product family | - | rel level | Released | | |
| appr | Rick Bian | 2013/07/22 | | | www.fci.com | cat. no. | - | Product - Customer Drw |
| FCI | | 2.00mm UNSHROUDED HEADER | | dwg no | 10121036 | | rev | B |
| | | BOARD TO BOARD THRU-HOLE | | | | | | |

